



PRODUCT DATASHEET



- PCB Reverse Mount
- 1206RV 1.1t Series
- ▶ Blue (470nm)

NOB13S94RV



1206RV 1.1t Series Compliant

FEATURES:

- Package: PCB Reverse Mount SMT Package
- Forward Current: 5mA
- Forward Voltage (typ.): 3.21V
- Luminous Intensity (typ.): 35mcd @5mA
- Colour: Blue
- Wavelength: 470nm
- Viewing angle: 130°
- Materials:
 - Die: InGaN
 - Resin: Epoxy (Water Clear)
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+90°C
- **ESD:** 150V
- Grouping parameters:
 - Forward voltage
 - Luminous intensity
 - Dominant Wavelength
- Soldering methods: Reflow
- **Preconditioning:** acc. to JEDEC Level 3
- Packing: 8mm tape with 2000/reel, ø180mm (7")

1206RV 1.1t Series

APPLICATIONS:

- Backlighting
- Indication Light
- Switch light



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	25	mA
Peak Forward Current Duty 1/10@10KHz	I _{FP}	100	mA
Reverse Current @5V	I _R	50	μΑ
Power Dissipation	P _D	110	mW
Electrostatic Discharge	ESD	150	V
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+90	°C

Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test
		Min.	Тур.	Max.	Om	Condition
Forward Voltage	V _F	2.7		3.7	V	I _F =5mA
Luminous Intensity	Iv	18		45	mcd	I _F =5mA
Dominant Wavelength	λ_{D}	465		475	nm	I _F =5mA
Viewing Angle	20 _{1/2}		130		deg	I _F =5mA

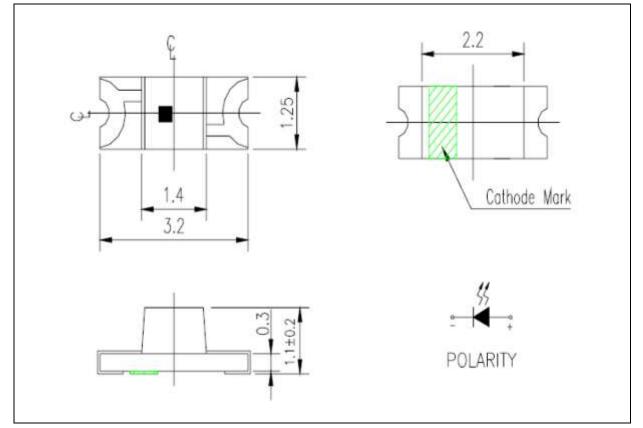
1. Luminous intensity (I_v) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle(2 $\theta_{1/2}$) ±5%

2. IS standard testing



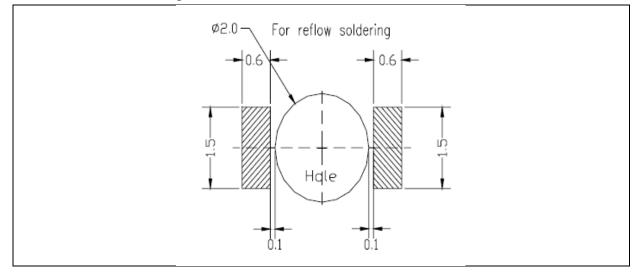
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ± 0.1 mm with angle tolerance $\pm 0.5^{\circ}$.



BINNING GROUPS:

Code Min. Max. Unit M1 18 22.5 M2 22.5 28.5 mcd 28.5 N1 36 N2 36 45

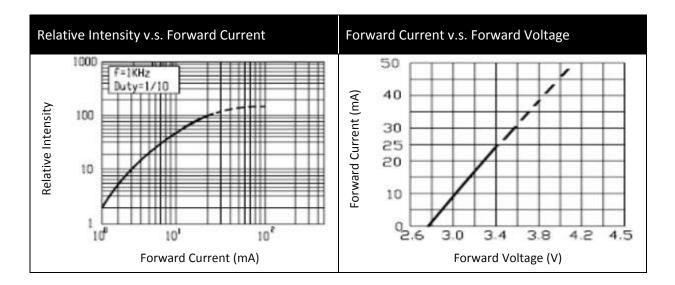
Luminous Intensity Classifications ($I_F = 5mA$):

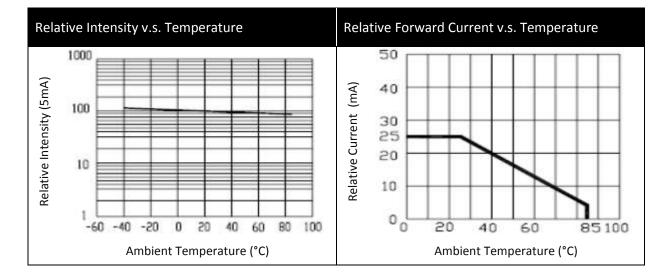
Dominant Wavelength Classifications (I_F = 5mA):

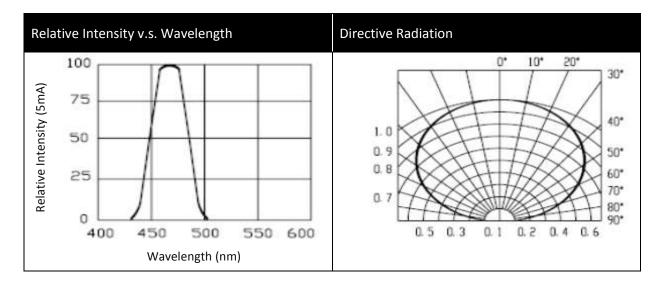
Code	Min.	Max.	Unit
X	465	470	2.22
Y	470 475		nm



ELECTRO-OPTICAL CHARACTERISTICS:



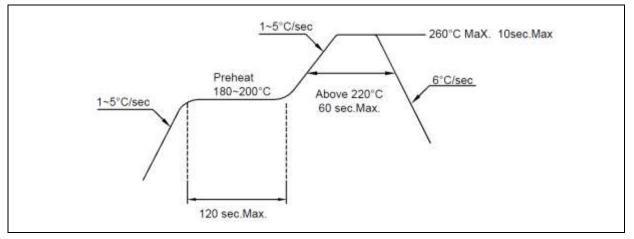






RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:



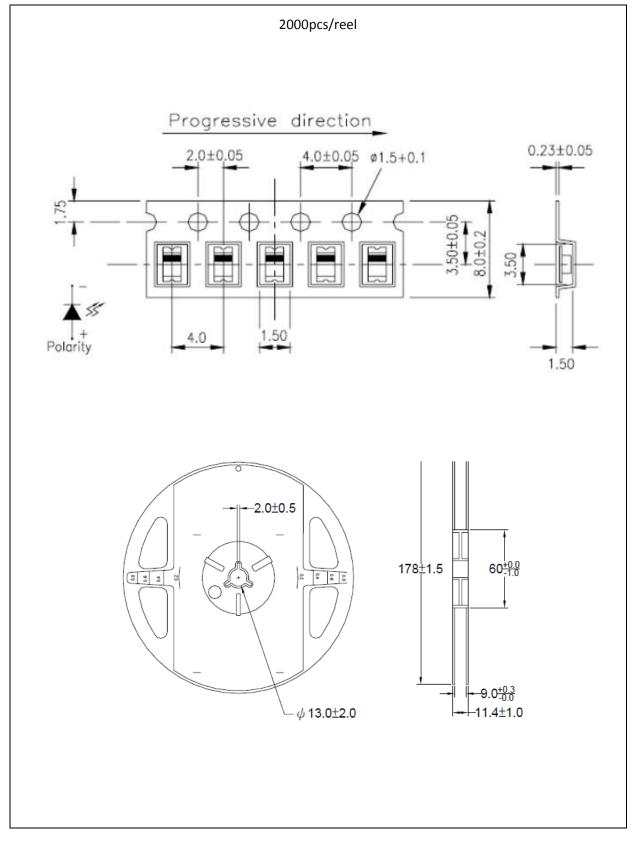
Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:



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PRECAUTIONS OF USE:



Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

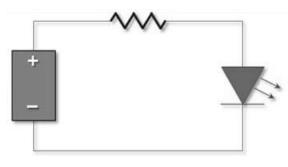
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

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REVISION RECORD:

Version	Date	Summary of Revision
A1.0	13/10/2014	Datasheet set-up.
A1.1	13/03/2015	Revise picture.
A1.2	16/03/2015	P/N add suffix RV indicating Reverse Mount.

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